

ABSTRACT

An object of the invention is to improve the position, shape, and size of a bump in order to realize highly reliable flip-chip mounting. In the case of the semiconductor device of this embodiment, a stacked bump 14 is provided on electrode pad 12 created on the main surface of semiconductor chip 10. That is, said bump 14 comprises columnar pedestal part 14a and columnar tail part 14b having a smaller diameter than that of pedestal part 14a. Peak plane of tail part 14b (peak plane of the bump) and the top surface of pedestal part 14a are both flat. Said bump 14 is created through gold plating, for example, using a resist (photolithography) technology and a plating technology.

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